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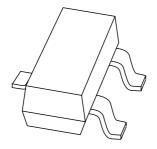
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS

DATA SHEET



BF824PNP medium frequency transistor

Product data sheet Supersedes data of 1999 Apr 15 2004 Jan 16



NXP Semiconductors Product data sheet

PNP medium frequency transistor

BF824

FEATURES

- Low current (max. 25 mA)
- Low voltage (max. 30 V).

APPLICATIONS

• RF stages in FM front-ends in common base configuration.

DESCRIPTION

PNP medium frequency transistor in a SOT23 plastic package.

MARKING

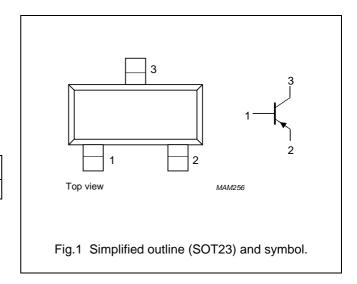
TYPE NUMBER	MARKING CODE(1)	
BF824	F8*	

Note

* = p : Made in Hong Kong.
 * = t : Made in Malaysia.
 * = W : Made in China.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



ORDERING INFORMATION

TYPE NUMBER	PACKAGE			
TIPE NOWIDER	NAME DESCRIPTION VERSION			
BF824	 plastic surface mounted package; 3 leads SOT		SOT23	

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NXP Semiconductors Product data sheet

PNP medium frequency transistor

BF824

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	_	-30	V
V_{CEO}	collector-emitter voltage	open base	_	-30	V
V _{EBO}	emitter-base voltage	open collector	_	-4	V
I _C	collector current (DC)		_	-25	mA
I _{CM}	peak collector current		_	-25	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	250	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	500	K/W

Note

1. Transistor mounted on an FR4 printed-circuit board.

CHARACTERISTICS

 $T_j = 25$ °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	$I_E = 0; V_{CB} = -30 \text{ V}$	_	_	-50	nA
I _{EBO}	emitter cut-off current	$I_C = 0; V_{EB} = -4 V$	_	_	-100	nA
h _{FE}	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -10 \text{ V}$	25	45	_	
		$I_C = -4 \text{ mA}; V_{CE} = -10 \text{ V}$	25	50	_	
V_{BE}	base-emitter voltage	$I_C = -4 \text{ mA}; V_{CE} = -10 \text{ V}$	_	_	-900	mV
C _{re}	feedback capacitance	$I_C = 0$; $V_{CE} = -10 \text{ V}$; $f = 1 \text{ MHz}$	_	_	0.3	pF
f _T	transition frequency	$V_{CE} = -10 \text{ V; } f = 100 \text{ MHz}$				
		$I_C = -1 \text{ mA}$	250	350	_	MHz
		$I_C = -4 \text{ mA}$	400	450	_	MHz
		$I_C = -8 \text{ mA}$	390	440	_	MHz

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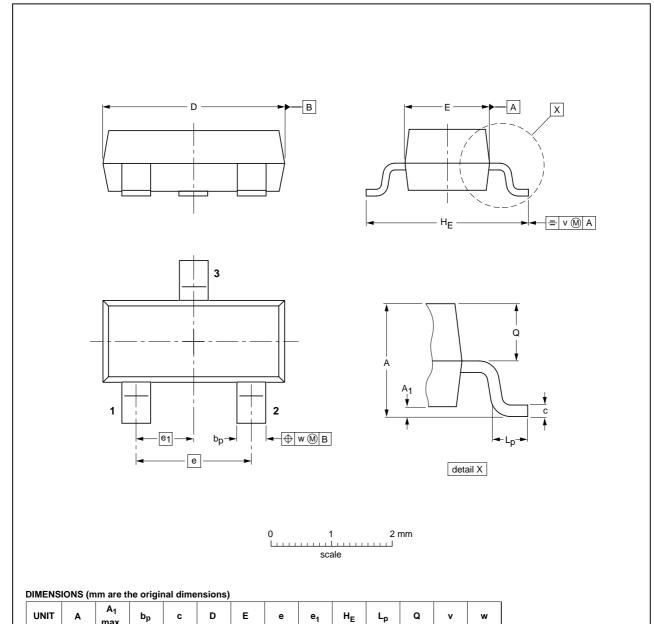
PNP medium frequency transistor

BF824

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT23



OUTLINE	REFERENCES		REFERENCES		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				04-11-04 06-03-16

0.45

0.55

0.1

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max

0.38

0.9

NXP Semiconductors Product data sheet

PNP medium frequency transistor

BF824

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
- The product status of device(s) described in this document may have changed since this document was published
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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com
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